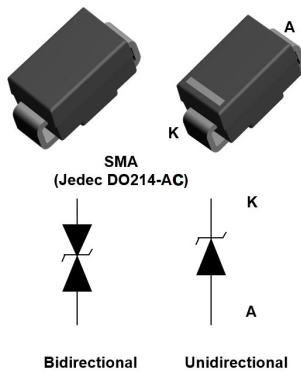



Automotive 400 W TVS in SMA



Product status link

[SM4T6V7AY](#), [SM4T6V7CAY](#),
[SM4T7V6AY](#), [SM4T7V6CAY](#),
[SM4T10AY](#), [SM4T10CAY](#),
[SM4T12AY](#), [SM4T12CAY](#),
[SM4T14AY](#), [SM4T14CAY](#),
[SM4T15AY](#), [SM4T15CAY](#),
[SM4T18AY](#), [SM4T18CAY](#),
[SM4T21AY](#), [SM4T21CAY](#),
[SM4T23AY](#), [SM4T23CAY](#),
[SM4T26AY](#), [SM4T26CAY](#),
[SM4T28AY](#), [SM4T28CAY](#),
[SM4T30AY](#), [SM4T30CAY](#),
[SM4T33AY](#), [SM4T33CAY](#),
[SM4T35AY](#), [SM4T35CAY](#),
[SM4T39AY](#), [SM4T39CAY](#),
[SM4T47AY](#), [SM4T47CAY](#),
[SM4T50AY](#), [SM4T50CAY](#),
[SM4T56AY](#), [SM4T56CAY](#),
[SM4T68AY](#), [SM4T68CAY](#),
[SM4T82AY](#), [SM4T82CAY](#)

Features

- AEC-Q101 qualified 
- Peak pulse power:
 - 400 W (10/1000 μ s)
 - 2.3 kW (8/20 μ s)
- Stand-off voltage range from 5 V to 70 V
- Unidirectional and bidirectional types
- Low leakage current:
 - 0.2 μ A at 25 °C
 - 1 μ A at 85 °C
- Operating T_j max: 150 °C
- JEDEC registered package outline
- Resin meets UL94, V0

Complies with the following standards

- ISO 10605, C = 150 pF, R = 330 Ω :
 - 30 kV (air discharge)
 - 30 kV (contact discharge)
- ISO 10605, C = 330 pF, R = 330 Ω :
 - 30 kV (air discharge)
 - 30 kV (contact discharge)
- ISO 7637-2 (not applicable to parts with V_{RM} lower than battery voltage 13.5 V):
 - Pulse 1: $V_S = -150$ V
 - Pulse 2a: $V_S = +112$ V
 - Pulse 3a: $V_S = -200$ V
 - Pulse 3b: $V_S = +150$ V

Description

The SM4TY series are designed to protect sensitive automotive circuits against surges defined in ISO 7637-2 and against electrostatic discharges according to ISO 10605.

The Planar technology makes it compatible with high-end circuits where low leakage current and high junction temperature are required to provide long term reliability and stability. SM4TY devices are packaged in SMA (SMA footprint in accordance with IPC 7531 standard).

1 Characteristics

Table 1. Absolute maximum ratings ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

| Symbol | Parameter | Value | Unit | |
|-----------|--|---|--------------------|----|
| V_{PP} | Peak pulse voltage | IEC 61000-4-2 (C = 150 pF, R = 330 Ω) | kV | |
| | | Contact discharge | | 30 |
| | | Air discharge | | 30 |
| | | ISO10605 (C = 330 pF, R = 330 Ω) | | |
| P_{PP} | Peak pulse power dissipation | T_j initial = T_{amb} | 400 | W |
| | | | | |
| T_{stg} | Storage temperature range | -65 to +150 | $^{\circ}\text{C}$ | |
| T_j | Operating junction temperature range | -55 to +150 | $^{\circ}\text{C}$ | |
| T_L | Maximum lead temperature for soldering during 10 s | 260 | $^{\circ}\text{C}$ | |

Figure 1. Electrical characteristics - parameter definitions

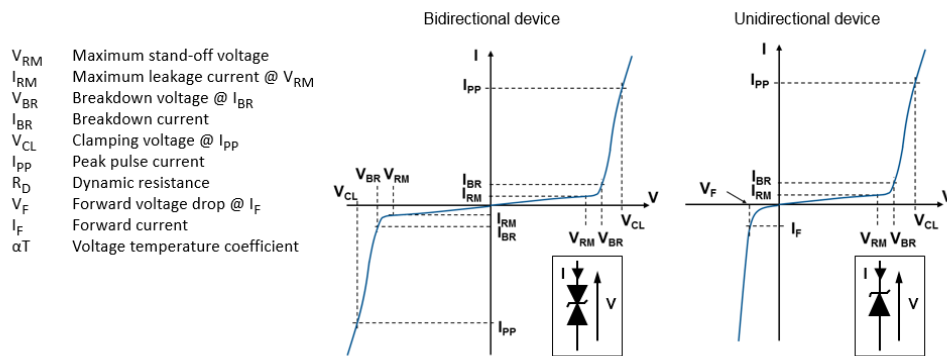


Figure 2. Pulse definition for electrical characteristics

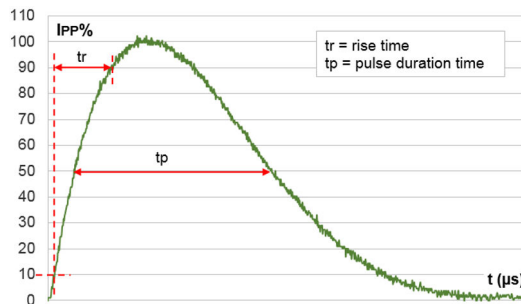


Table 2. Electrical characteristics - parameter values ($T_{amb} = 25\text{ °C}$, unless otherwise specified)

| Type | I_{RM} max at V_{RM} | | | V_{BR} at $I_{BR}^{(1)}$ | | | | 10 / 1000 μ s | | | 8 / 20 μ s | | | αT |
|---------------|--------------------------|---------|-----|----------------------------|------|------|----|-------------------|----------------|----------|-------------------|----------------|----------|---------------------|
| | | | | | | | | $V_{CL}^{(2)(3)}$ | $I_{PP}^{(4)}$ | R_D | $V_{CL}^{(2)(3)}$ | $I_{PP}^{(4)}$ | R_D | |
| | 25 °C | 85 °C | | Min. | Typ. | Max. | | Max. | | Max. | Max. | | Max. | |
| | μ A | μ A | V | V | V | V | mA | V | A | Ω | V | A | Ω | $10^{-4}/\text{°C}$ |
| SM4T6V7AY/CAY | 20 | 50 | 5 | 6.4 | 6.74 | 7.1 | 10 | 9.2 | 43.5 | 0.049 | 13.4 | 174 | 0.036 | 5.7 |
| SM4T7V6AY/CAY | 20 | 50 | 6.5 | 7.2 | 7.58 | 8 | 10 | 11.2 | 35.7 | 0.091 | 14.5 | 160 | 0.041 | 6.1 |
| SM4T10AY/CAY | 20 | 50 | 8.5 | 9.4 | 9.9 | 10.4 | 1 | 14.4 | 27.7 | 0.145 | 19.5 | 124 | 0.073 | 7.3 |
| SM4T12AY/CAY | 0.2 | 1 | 10 | 11.1 | 11.7 | 12.3 | 1 | 17 | 23.5 | 0.201 | 21.7 | 106 | 0.089 | 7.8 |
| SM4T14AY/CAY | 0.2 | 1 | 12 | 13.3 | 14 | 14.7 | 1 | 19.9 | 20.1 | 0.259 | 25.3 | 91 | 0.116 | 8.3 |
| SM4T15AY/CAY | 0.2 | 1 | 13 | 14.4 | 15.2 | 16 | 1 | 21.5 | 18.6 | 0.298 | 27.2 | 85 | 0.132 | 8.4 |
| SM4T18AY/CAY | 0.2 | 1 | 15 | 16.7 | 17.6 | 18.5 | 1 | 24.4 | 16.4 | 0.361 | 32.5 | 71 | 0.197 | 8.8 |
| SM4T21AY/CAY | 0.2 | 1 | 18 | 20.0 | 21.1 | 22.2 | 1 | 29.2 | 13.7 | 0.514 | 39.3 | 59 | 0.291 | 9.2 |
| SM4T23AY/CAY | 0.2 | 1 | 20 | 22.2 | 23.4 | 24.6 | 1 | 32.4 | 12.3 | 0.637 | 42.8 | 54 | 0.338 | 9.4 |
| SM4T26AY/CAY | 0.2 | 1 | 22 | 24.4 | 25.7 | 27 | 1 | 35.5 | 11.2 | 0.760 | 48.3 | 48 | 0.444 | 9.6 |
| SM4T28AY/CAY | 0.2 | 1 | 24 | 26.7 | 28.1 | 29.5 | 1 | 38.9 | 10.3 | 0.912 | 50 | 46 | 0.446 | 9.6 |
| SM4T30AY/CAY | 0.2 | 1 | 26 | 28.9 | 30.4 | 31.9 | 1 | 42.1 | 9.5 | 1.07 | 53.5 | 43 | 0.502 | 9.7 |
| SM4T33AY/CAY | 0.2 | 1 | 28 | 31.1 | 32.7 | 34.3 | 1 | 45.4 | 8.8 | 1.26 | 59 | 39 | 0.632 | 9.8 |
| SM4T35AY/CAY | 0.2 | 1 | 30 | 33.3 | 35.1 | 36.9 | 1 | 48.4 | 8.3 | 1.39 | 64.3 | 36 | 0.762 | 9.9 |
| SM4T39AY/CAY | 0.2 | 1 | 33 | 36.7 | 38.6 | 40.5 | 1 | 53.3 | 7.5 | 1.70 | 69.7 | 33 | 0.884 | 10 |
| SM4T47AY/CAY | 0.2 | 1 | 40 | 44.4 | 46.7 | 49 | 1 | 64.5 | 6.2 | 2.49 | 84 | 27 | 1.30 | 10.1 |
| SM4T50AY/CAY | 0.2 | 1 | 43 | 47.8 | 50.3 | 52.8 | 1 | 69.4 | 5.7 | 2.91 | 91 | 25 | 1.53 | 10.2 |
| SM4T56AY/CAY | 0.2 | 1 | 48 | 53.3 | 56.1 | 58.9 | 1 | 77.4 | 5.2 | 3.56 | 100 | 23 | 1.79 | 10.3 |
| SM4T68AY/CAY | 0.2 | 1 | 58 | 64.4 | 67.8 | 71.2 | 1 | 93.6 | 4.3 | 5.21 | 121 | 19 | 2.62 | 10.4 |
| SM4T82AY/CAY | 0.2 | 1 | 70 | 77.8 | 81.9 | 86 | 1 | 113 | 3.5 | 7.72 | 146 | 16 | 3.75 | 10.5 |

1. To calculate V_{BR} versus T_j : V_{BR} at $T_j = V_{BR}$ at $25\text{ °C} \times (1 + \alpha T \times (T_j - 25))$
2. To calculate V_{CL} versus T_j : V_{CL} at $T_j = V_{CL}$ at $25\text{ °C} \times (1 + \alpha T \times (T_j - 25))$
3. To calculate V_{CL} max. versus I_{PP} appli: $V_{CL} \text{ max.} = V_{BR} \text{ max.} + R_D \times I_{PP} \text{ appli.}$
4. Surge capability given for both directions for unidirectional and bidirectional devices

1.1 Characteristics (curves)

Figure 3. Maximum peak power dissipation versus initial junction temperature

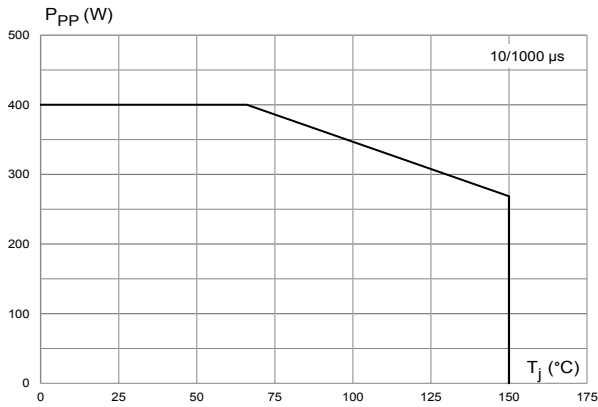


Figure 4. Maximum peak pulse power versus exponential pulse duration

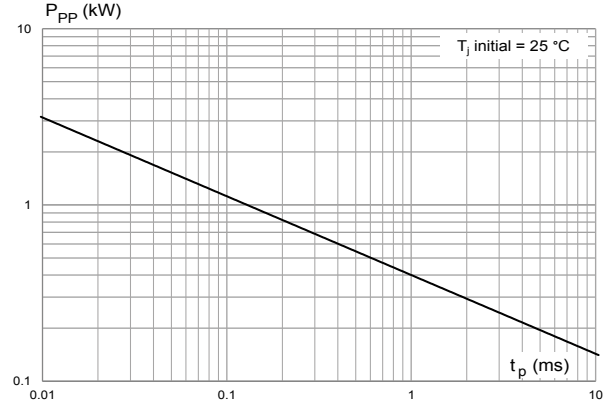


Figure 5. Maximum peak pulse current versus clamping voltage

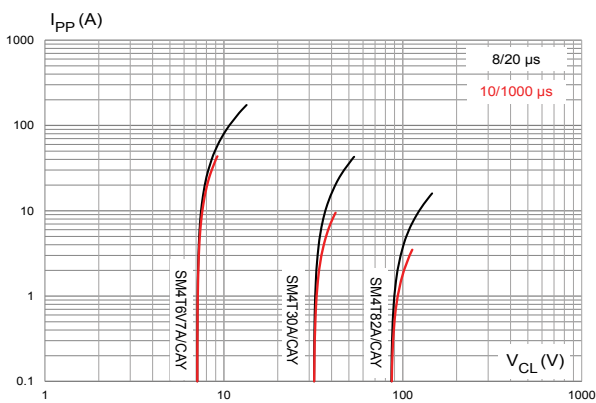


Figure 6. Dynamic resistance versus pulse duration

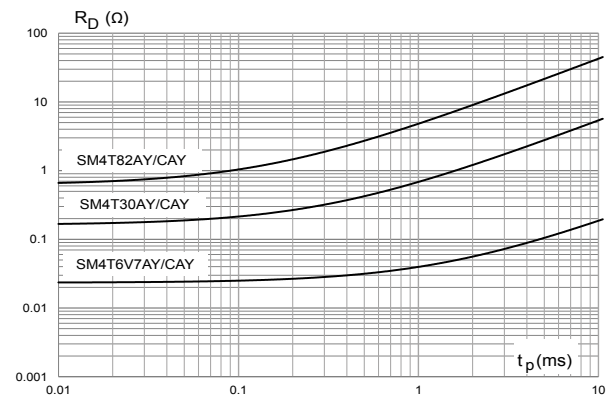


Figure 7. Junction capacitance versus reverse applied voltage (unidirectional type)

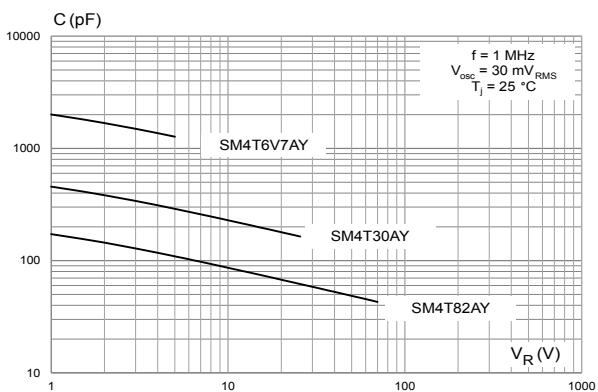


Figure 8. Junction capacitance versus applied voltage (bidirectional type)

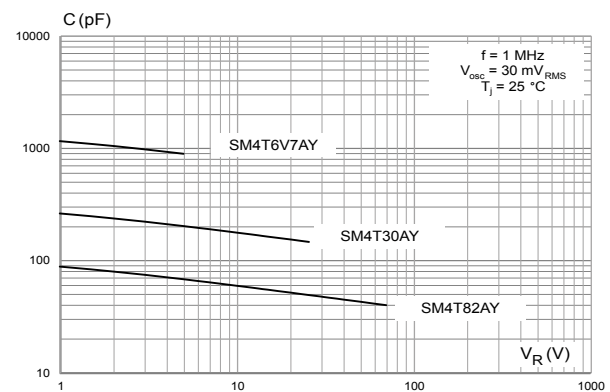


Figure 9. Leakage current versus junction temperature

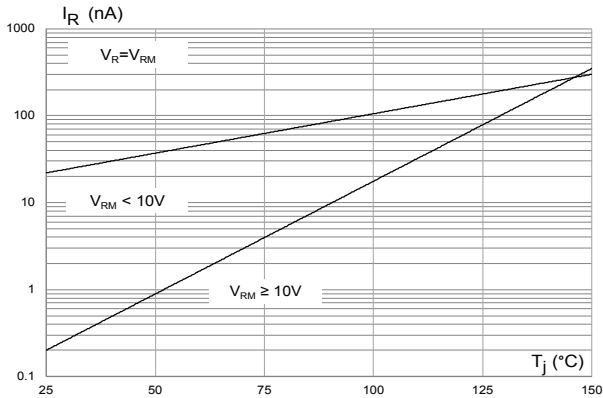


Figure 10. Peak forward voltage drop versus peak forward current

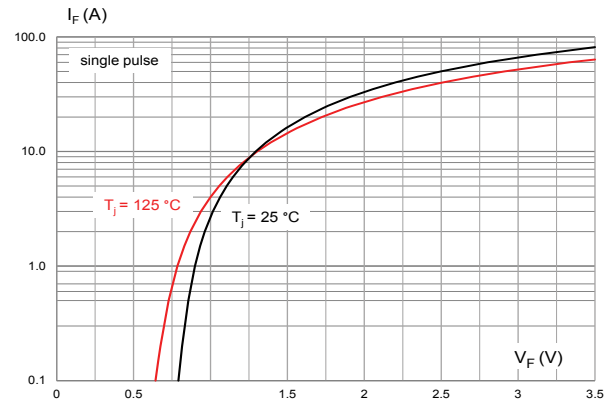


Figure 11. Thermal impedance junction to ambient versus pulse duration

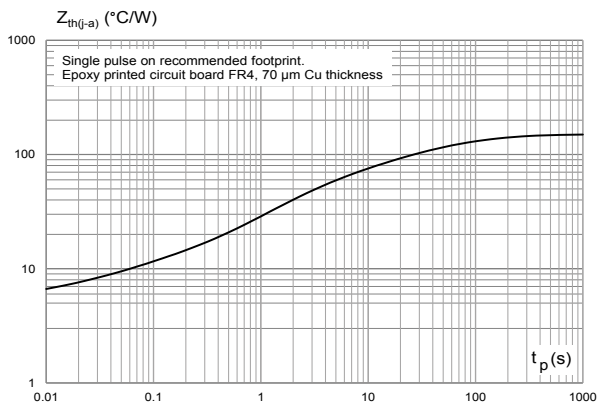


Figure 12. Thermal resistance junction to ambient versus copper area under each lead

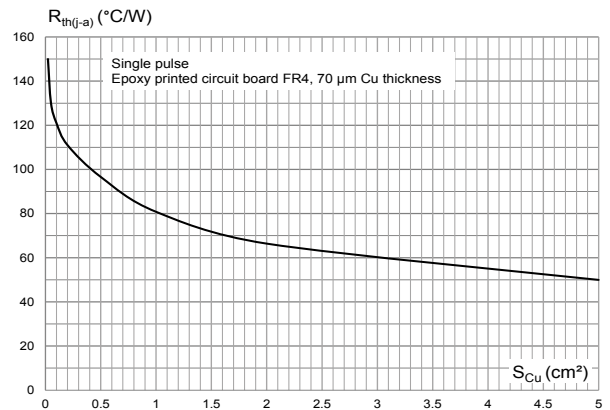


Figure 13. ISO7637-2 pulse 1: $V_s = -150\text{ V}$ with 12 V battery

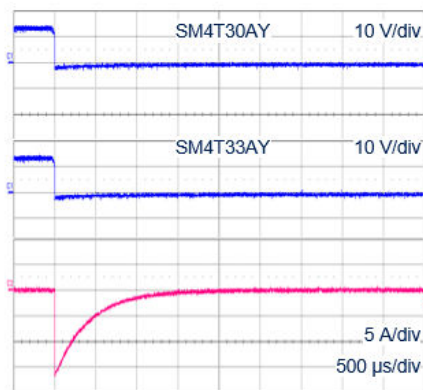


Figure 14. ISO7637-2 pulse 2a: $V_s = +112\text{ V}$ with 12 V battery

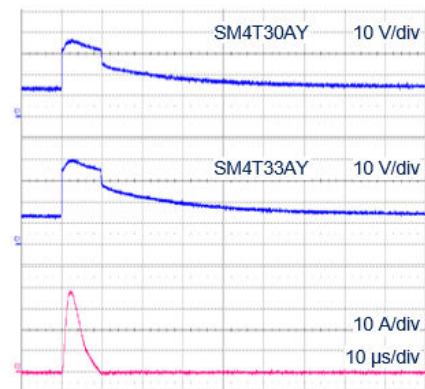


Figure 15. ISO7637-2 pulse 3a: $V_s = -220\text{ V}$ with 12 V battery

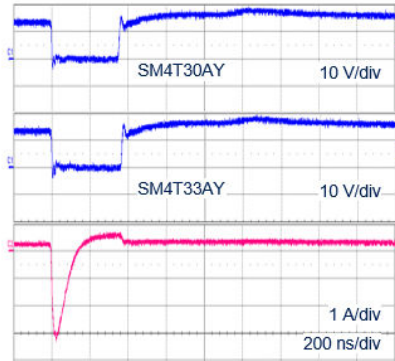
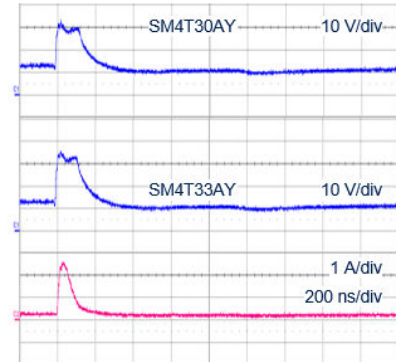


Figure 16. ISO7637-2 pulse 3b: $V_s = +150\text{ V}$ with 12 V battery



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 SMA package information

Figure 17. SMA package outline

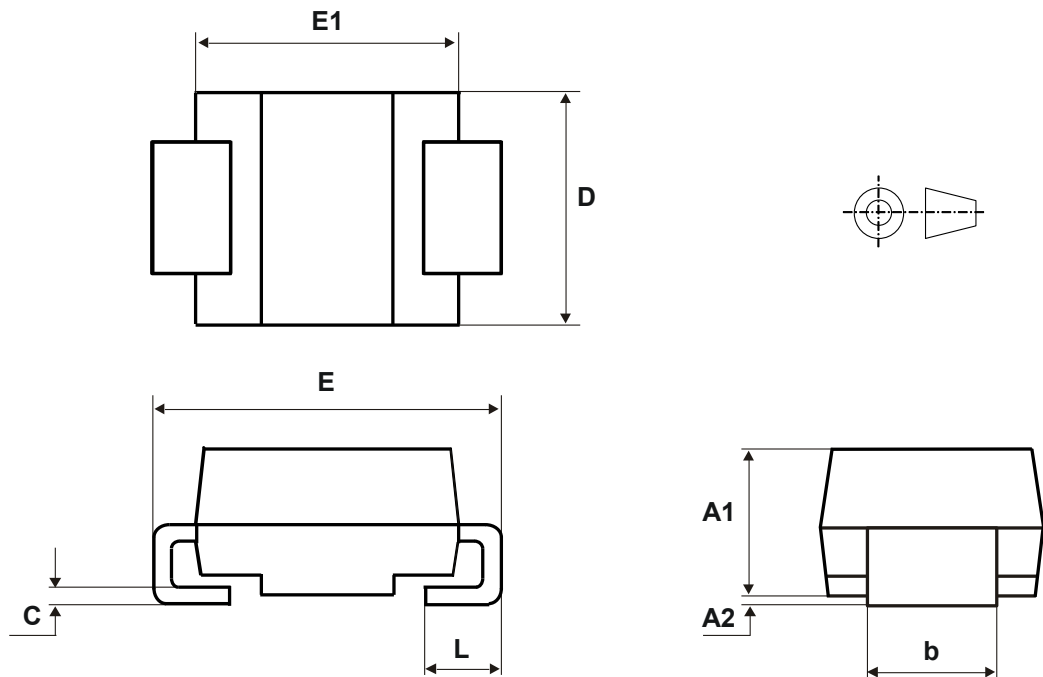


Table 3. SMA package mechanical data

| Ref. | Dimensions | | | |
|------|-------------|------|-----------------------|-------|
| | Millimeters | | Inches ⁽¹⁾ | |
| | Min. | Max. | Min. | Max. |
| A1 | 1.90 | 2.45 | 0.074 | 0.097 |
| A2 | 0.05 | 0.20 | 0.001 | 0.008 |
| b | 1.25 | 1.65 | 0.049 | 0.065 |
| c | 0.15 | 0.40 | 0.005 | 0.016 |
| D | 2.25 | 2.90 | 0.088 | 0.115 |
| E | 4.80 | 5.35 | 0.188 | 0.211 |
| E1 | 3.95 | 4.60 | 0.155 | 0.182 |
| L | 0.75 | 1.50 | 0.029 | 0.060 |

1. Values in inches are converted from mm.

Figure 18. SMA recommended footprint in mm (inches)

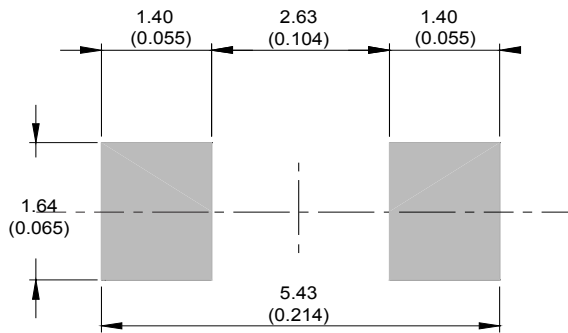


Figure 19. SMA marking

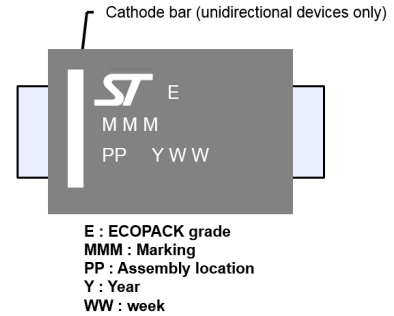
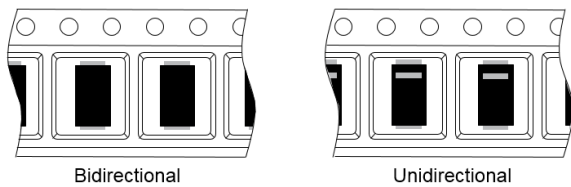


Figure 20. Package orientation in reel



Taped according to EIA-481
Pocket dimensions are not on scale.
Pocket shape may vary depending on package
On bidirectional devices, marking and logo may not be always in the same direction.

Figure 21. Tape and reel orientation

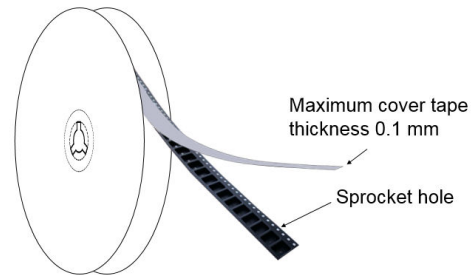


Figure 22. 13" reel dimension values (mm)

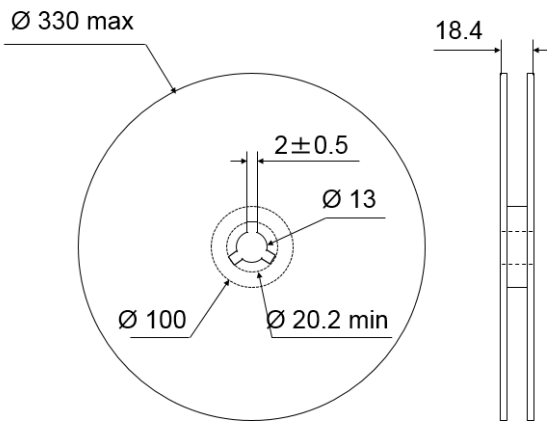


Figure 23. Inner box dimension values (mm)

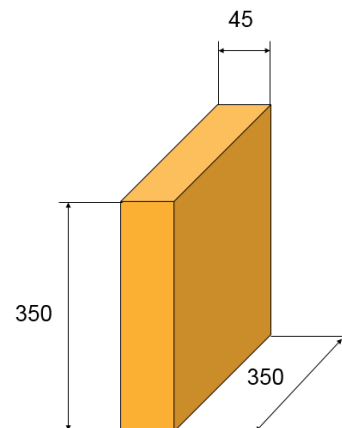
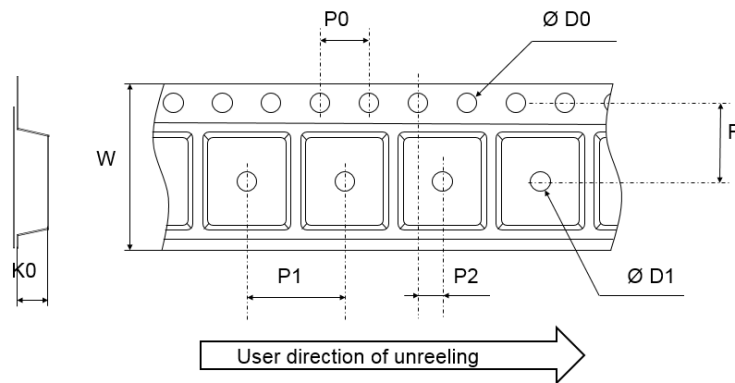


Figure 24. Tape outline



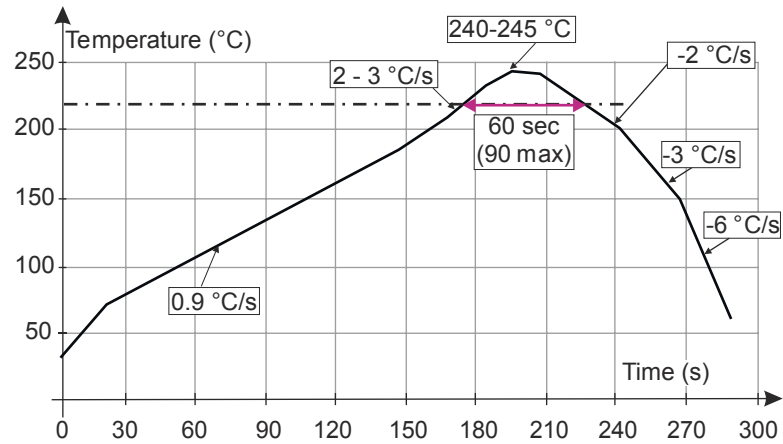
Note: Pocket dimensions are not on scale
Pocket shape may vary depending on package

Table 4. Tape dimension values

| Ref. | Dimensions | | |
|------|-------------|-------|-------|
| | Millimeters | | |
| | Min. | Typ. | Max. |
| D0 | 1.40 | 1.50 | 1.60 |
| D1 | 1.50 | | |
| F | 5.40 | 5.50 | 5.60 |
| K0 | 2.26 | 2.36 | 2.46 |
| P0 | 3.90 | 4.00 | 4.10 |
| P1 | 3.90 | 4.00 | 4.10 |
| P2 | 1.95 | 2.00 | 2.05 |
| W | 11.70 | 12.00 | 12.30 |

2.2 Reflow profile

Figure 25. ST ECOPACK recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement. Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

3 Application and design guidelines

More information is available in the application note AN2689 “Protection of automotive electronics from electrical hazards, guidelines for design and component selection”.

4 Ordering information

Table 5. Ordering information

| Order code | Marking | Package | Weight | Base qty. | Delivery mode |
|-----------------------------|-----------------------|---------|--------|-----------|---------------|
| SM4TxxAY/CAY ⁽¹⁾ | See Table 6. Marking. | SMA | 72 mg | 5000 | Tape and reel |

1. Where xx is nominal value of V_{BR} and A or CA indicates unidirectional or bidirectional version.

Table 6. Marking

| Order code | Marking | Order code | Marking |
|------------|---------|------------|---------|
| SM4T6V7AY | AEY | SM4T6V7CAY | AAAY |
| SM4T7V6AY | DUCY | SM4T7V6CAY | DBCY |
| SM4T10AY | DUHY | SM4T10CAY | DBHY |
| SM4T12AY | AXY | SM4T12CAY | ACY |
| SM4T14AY | DUKY | SM4T14CAY | DBKY |
| SM4T15AY | BGY | SM4T15CAY | BHY |
| SM4T18AY | BMY | SM4T18CAY | AJY |
| SM4T21AY | DUQY | SM4T21CAY | DBQY |
| SM4T23AY | DURY | SM4T23CAY | DBRY |
| SM4T26AY | DUSY | SM4T26CAY | DBSY |
| SM4T28AY | DUTY | SM4T28CAY | DBTY |
| SM4T30AY | DUUY | SM4T30CAY | DBUY |
| SM4T33AY | CGY | SM4T33CAY | CHY |
| SM4T35AY | CKY | SM4T35CAY | CLY |
| SM4T39AY | CMY | SM4T39CAY | CNY |
| SM4T47AY | DUZY | SM4T47CAY | DBZY |
| SM4T50AY | EUAY | SM4T50CAY | EBAY |
| SM4T56AY | CXY | SM4T56CAY | CYY |
| SM4T68AY | EUFY | SM4T68CAY | EBFY |
| SM4T82AY | EUIY | SM4T82CAY | EBIY |

Revision history

Table 7. Document revision history

| Date | Version | Changes |
|-------------|---------|--|
| 08-Sep-2010 | 1 | Initial release. |
| 09-Nov-2011 | 2 | Added order codes in Table 2 and Table 4. Updated Figure 5, 6 and 7. |
| 27-Mar-2012 | 3 | Added footnote on page 1. |
| 05-Oct-2015 | 4 | Updated Table 1. |
| 26-Jan-2022 | 5 | Minor text changes. |
| 13-Jul-2023 | 6 | Updated Figure 9 . |

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